

Abstract**A structuring method**

- 5 The invention provides a structuring method, in particular for stepped wafer or die surfaces. The method includes photolithographically exposing a pattern comprising at least a first pattern portion and a second pattern portion onto a surface, said surface comprising at least a first
10 surface portion at which a tangential plane to the surface extends in a first plane and a second surface portion at which a tangential plane to the surface extends in a second plane not coinciding with the first plane. The method comprises a first exposure step, in which the first pattern portion is exposed. Therein, the first pattern portion is focused into a first focal plane. The method further comprises a second exposure step, in which the second pattern portion is exposed. Therein, the second pattern portion is focused into a second focal plane which
15 is different from the first focal plane.
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